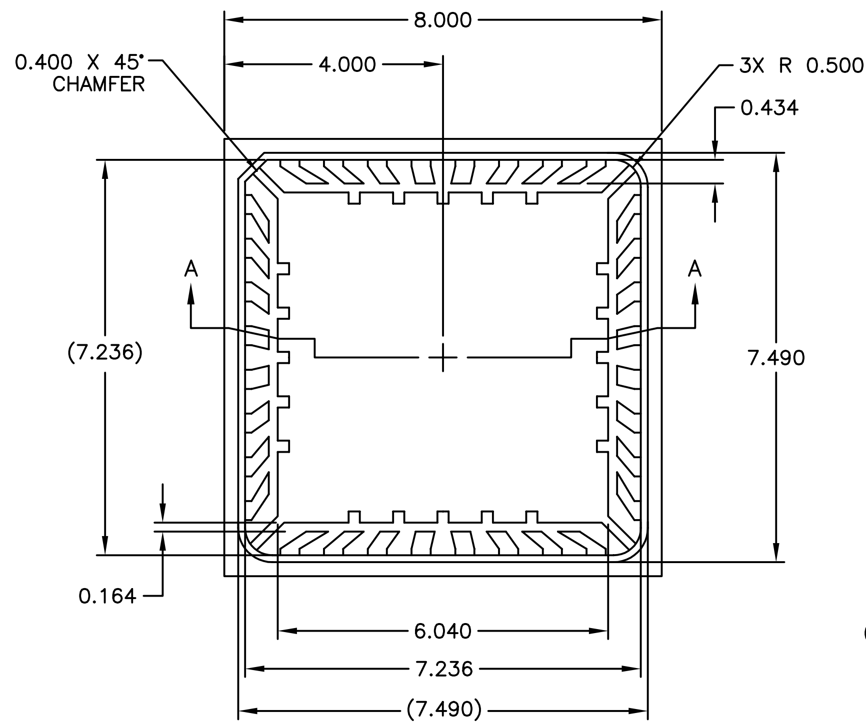
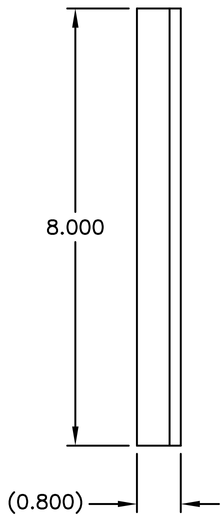
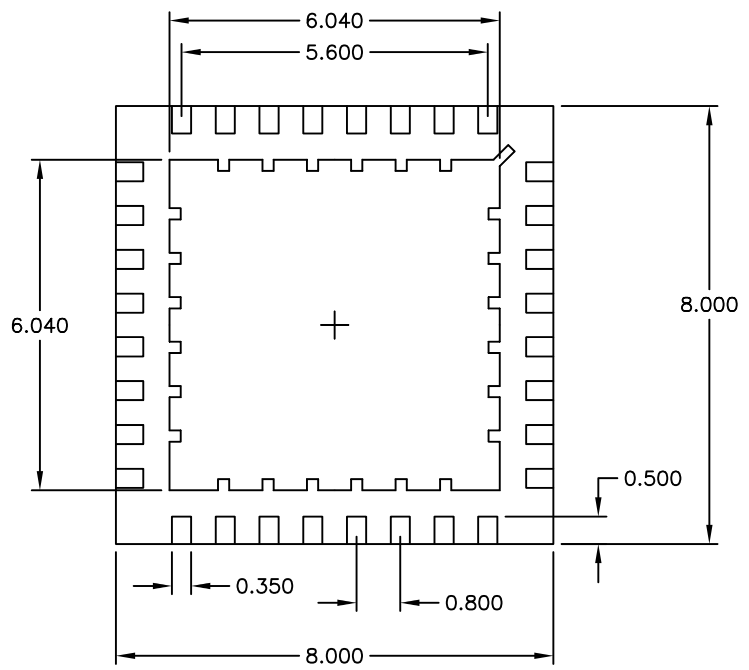
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10609	2/28/06	PRODUCTION RELEASE	D.BENANDO

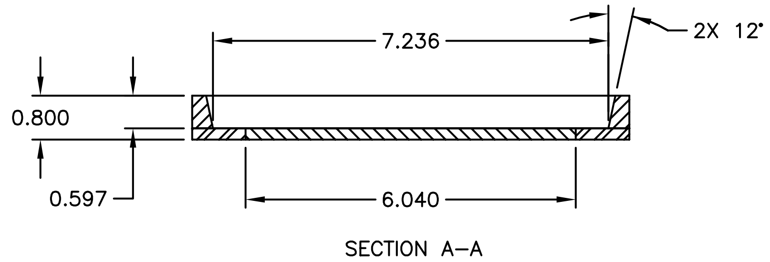


TOP VIEW



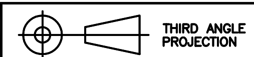


BOTTOM VIEW



SECTION A–A

NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ±.0076.
6. DIE PAD: 6.040 X 6.040.
7. JEDEC OUTLINE: MO–220 (VLLB).



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
X.XX ± 0.15 X.XXXX ± –––
X.XXX ± 0.100 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	2/28/06
APP BY	P. FLASKERUD	DATE	2/28/06
CUSTOMER	–––		

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SEMPAC, INC.
Open-Pak™ Technologies
www.sempac.com
568 E. WEDDELL DRIVE, SUITE 5
SUNNYVALE, CALIFORNIA 94089
PHONE: (408) 400-9002 FAX: (408) 400-9006

32 Lead 8mm x 8mm MLP Open–Pak

SIZE	PART NO.	REV
A	MLP8X8–32–OP–01	1
SCALE NONE	CAD FILE MLP8X8–32–OP–01–R1.DWG	SHEET 1 OF 1

BORDER–AHM–1.DWG
REV 1 ECN 10595